Form 1449 (Modified)	Atty. Docket No. HIT1P057/ HSJ920030250US1	Application No.: Unassigned
Information Disclosure	Applicant:	
Statement By Applicant	Guthrie et al.	
	Filing Date:	Group Art Unit:
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.